

WHAT IS CLAIMED IS:

1. A burn-in test adapter, to which an assembly substrate on which a plurality of semiconductor chips each having a terminal receiving a burn-in test waveform are arranged is detachably attached, comprising:
5 a wiring provided in such a manner that, when the assembly substrate is attached to the burn-in test adapter, the wiring makes an electrical contact with the terminal of each of the semiconductor chips on the assembly substrate; and
a burn-in test terminal electrically connected to the wiring and
10 receiving the burn-in test waveform.
2. The burn-in test adapter according to claim 1, further comprising a burn-in test waveform generation circuit that increases the number of the burn-in test waveforms, and that is provided on the wiring at
15 positions that correspond to positions of the individual semiconductor chips when the assembly substrate is attached to the burn-in test adapter.
3. The burn-in test adapter according to claim 1, wherein the
20 burn-in test adapter is rectangular, and the burn-in test terminal is arranged on one of the four sides of the burn-in test adapter.
4. A burn-in test apparatus comprising:
a burn-in test adapter, to which an assembly substrate on which
25 a plurality of semiconductor chips each having a terminal receiving a

burn-in test waveform are arranged is detachably attached, the burn-in test adapter including

a wiring provided in such a manner that, when the assembly substrate is attached to the burn-in test adapter, the wiring
5 makes an electrical contact with the terminal of each of the semiconductor chips on the assembly substrate; and

a burn-in test terminal that is electrically connected to the wiring and receives the burn-in test waveform, wherein the burn-in test adapter is rectangular, and the burn-in test terminal is arranged on
10 one of the four sides of the burn-in test adapter;

a socket that holds the burn-in test adapter at the side on which the burn-in test terminal is arranged and that is electrically connected to the burn-in test terminal; and

a burn-in board that holds the socket and that includes a wiring
15 that is electrically connected to the socket, wherein the wiring receives the burn-in test waveform.

5. The burn-in test apparatus according to claim 4, wherein the sockets are provided in plurality.

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6. A burn-in test adapter, to which an assembly substrate on which a plurality of semiconductor chips each having a chip-side terminal for receiving a burn-in test waveform are arranged is detachably attached, comprising:

25 an adapter-side terminal corresponding to each chip-side

terminal, wherein the adapter-side terminal is arranged at such a position that when the assembly substrate is attached to the burn-in test adapter the adapter-side terminal makes an electrical contact with the corresponding chip-side terminal;

- 5 a signal receiving terminal that receives the burn-in test waveform; and

 a wiring that electrically connects the adapter-side terminal to the signal receiving terminal.